Electronic Acknowledgement Receipt			
EFS ID:	1218281		
Application Number:	10632568		
Confirmation Number:	2603		
Title of Invention:	Semiconductor multi-package module having package stacked over ball grid array package and having wire bond interconnect between stacked packages		
First Named Inventor:	Marcos Karnezos		
Customer Number:	22470		
Filer:	Bill Kennedy/Paula Hurley		
Filer Authorized By:	Bill Kennedy		
Attorney Docket Number:	CPAC 1017-3		
Receipt Date:	25-SEP-2006		
Filing Date:	02-AUG-2003		
Time Stamp:	17:11:16		
Application Type:	Utility		
International Application Number:			
Payment information:			
Submitted with Payment	yes		
Payment was successfully received in RAM	\$180		

File Listing:			
	Deposit Account		
	RAM confirmation Number	485	

Document Number	Document Description	

File Name	File Size(Byte
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1	Information Disclosure Statement (IDS) Filed	efsids20060925.pdf	100146	no	3		
Warnings:							
Information:							
This is not an USPTO supplied IDS fillable form							
2	Fee Worksheet (PTO-875)	fee-info.pdf	8224	no	2		
Warnings:							
Information:							
Total Files Size (in bytes): 108370							

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.